[0262] In addition, the wireless communication module **7400** may further have a function of allowing the user to partially modify the illumination pattern received from the server **7300** and/or the information storage device **7600** or manipulate a new illumination pattern when necessary or desired. The modified or newly manipulated "user setting illumination pattern" may be stored in the wireless communication module **7400**, may be automatically transmitted to the server **7300** and/or the information storage device **7600**, or may be transmitted when necessary or desired (e.g., according to a user request). In addition, the wireless communication module **7400** may automatically receive the "defined illumination pattern" and the "normal illumination pattern" from the server **7300** and/or the information storage device **7600**, or may receive the "defined illumination pattern" and the "normal illumination pattern" by transmitting a provision request signal to the server **7300**.

[0263] The wireless communication module **7400** may exchange a command or information signal with the server **7300** and/or the information storage device **7600**, and the server **7300** may serve as a medium between the wireless communication module **7400**, the sensor module **7200**, and the controller **7500**. In this manner, the smart lighting system may be operated.

[0264] The connection between the wireless communication module **7400** and the server **7300** may be performed using an application program of the smartphone. That is, the user may instruct the server **7300** to execute the "automatic illumination mode" through an application program downloaded in the smartphone, or may provide information about the user setting illumination pattern" manipulated or modified by the user.

[0265] The information may be automatically provided to the server **7300** and/or the information storage device **7600** by the storing of the "user setting illumination pattern", or may be provided by performing a transmission operation. This feature may be set as a default of the application program, or may be selected by the user according to an option.

[0266] The controller **7500** may receive the command signal of executing or stopping the "automatic illumination mode" from the server **7300**, and control one or more lighting apparatuses by executing the received command signal in the illumination module **7100**. That is, the controller **7500** may control the turn-on/off or the like of the lighting apparatuses included in the illumination module **7100** according to the command signal from the server **7300**.

[0267] In addition, the smart lighting system **7000** may further include an alarm device **7700** in the building. The alarm device **7700** may output an alarm according to various criteria, e.g., when the alarm device **7700** detects that there is an intruder in the building.

[0268] Specifically, in a case where the "automatic illumination mode" is executed in the building in the absence of the user, when there occurs an intrusion in the building and there occurs an abnormal situation deviating from the set illumination pattern, the sensor module **7200** may detect the abnormal situation and transmit an alarm signal to the server **7300**. The server **7300** may notify the wireless communication module **7400** of the abnormal situation and operate the alarm device **7700** in the building by transmitting a signal to the controller **7500**.

[0269] In addition, when the alarm signal is transmitted to the server **7300**, the server **7300** may directly notify a security company of an emergency situation via the wireless communication module **7400** or a TCP/IP network.

[0270] While the exemplary embodiments have been particularly shown and described with reference to certain exemplary embodiments thereof, it will be understood that various changes in form and details may be made therein without departing from the spirit and scope of the following claims.

What is claimed is:

1. A light-emitting diode (LED) package comprising:

a light-emitting structure comprising a first conductive-type semiconductor layer, an active layer provided on the first conductive-type semiconductor layer, and a second conductive-type semiconductor layer provided on the active layer;

an isolating insulation layer provided on two side portions of the light-emitting structure and an upper portion of the light-emitting structure, the upper portion connecting the two side portions;

a first connection electrode portion electrically connected to the first conductive-type semiconductor layer;

a second connection electrode portion electrically connected to the second conductive-type semiconductor layer;

a first electrode pad electrically connected to the first connection electrode portion;

a second electrode pad electrically connected to the second connection electrode portion;

a first molding resin layer provided between the first electrode pad and the second electrode pad;

a first pillar electrode electrically connected to the first electrode pad;

a second pillar electrode electrically connected to the second electrode pad; and

a second molding resin layer provided on the first molding resin layer, the first electrode pad, and the second electrode pad, and between the first pillar electrode and the second pillar electrode.

2. The LED package of claim **1**, wherein the first molding resin layer comprises a material layer which has a reflectivity that is higher than a reflectivity of the second molding resin layer, and the second molding resin layer comprises a material layer which has a reliability that is higher than a reliability of the first molding resin layer.

3. The LED package of claim **1**, wherein the first molding resin layer is an encapsulation layer sealing a gap between the first electrode pad and the second electrode pad.

4. The LED package of claim **3**, further comprising a first reflective layer provided on the first molding resin layer.

5. The LED package of claim **4**, further comprising a second reflective layer provided between the first molding resin layer and the second molding resin layer.

6. The LED package of claim **1**, wherein the first molding resin layer contacts a surface and a side wall of the first electrode pad, a surface and a sidewall of the second electrode pad, a side wall of the first pillar electrode, and a sidewall of the second pillar electrode, and

the second molding resin layer contacts the first molding resin layer.

7. The LED package of claim **1**, wherein the second molding resin layer is an encapsulation layer sealing a gap between the first pillar electrode and the second pillar electrode.